

## CLAIMS

We claim:

1        1. A method for attaching a module to a printed circuit board comprising  
2        the steps of:

3            attaching a standoff to the module;

4            applying a ball grid array to the module;

5            positioning the module such that the standoff is between the printed  
6        circuit board and the module; and

7            reflowing the ball grid array.

1        2. An electrical attachment comprising:

2            a module having connection pads on a bottom surface;

3            a standoff, positioned on the bottom surface, having a height;

4            a printed circuit board having connection pads;

5            a ball grid array, interposing the connection pads of the module and the  
6        printed circuit board, wherein the height of the ball grid array is comparable to  
7        the height of the standoff.

1        3. An electrical attachment, as defined in claim 2, wherein the standoff is  
2        an insulative material.

1        4. An electrical attachment, as defined in claim 3, wherein the insulative  
2        material is silicon.

1        5. An electrical attachment, as defined in claim 2, further comprising a  
2        flexible circuit interposing the module and the standoff.

1        6. An electrical attachment, as defined in claim 5, wherein the standoff is  
2        an insulative material.

1        7. An electrical attachment, as defined in claim 6, wherein the insulative  
2        material is silicon.